

- transferring the module onto the support body, a first circuit (8, 30) of the module connecting said terminals (32) of the second circuit.

5           9.    The method according to claim 8, characterised in that the step of connecting the module to the connection terminals (32) takes place during the fixing of the module (17) to the support body, the pins (30) connecting said connection terminals (32) of the support body.

10           10.   The method according to claim 9, characterised in that it comprises a step of depositing conductive material on said terminals (32).

15           11.   The method according to either claim 1 or claim 2, characterised in that the interconnection elements (9C, 19C) are disposed solely within the periphery of the module.

20           12.   The method according to claim 1, characterised in that the interconnection elements (9C, 19C) are held in place on or above or along an interconnection zone Z by adhesion.

25           13.   The method according to claim 12, characterised in that the adhesion is effected via an adhesive for inserting the module or by thermocompression or thermoadhesion on an adhesive surface of the module.

14.   The method according to any of the preceding claims, characterised in that said circuit comprises an antenna or a display or a keypad or a switch.